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What is claimed is:

1. A lead-free solder consisting essentially of:

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- 1.0 to 4.0 wt% of Ag;
- (b)
- 0.4 to 1.3 wt% of Cu;
- (c)
- 0.02 to 0.0% wt% of Ni; and
- (d)
- a balance/of Sn;

wherein said Ni serves to lower a copper dissolution rate of said solder.

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- The solder according to claim 1, wherein a content of Ni is in a range from 0.02 to 0.04 wt%.
- 3. The solder according to clafm 1, wherein said solder having a copper dissolution rate of 0.20 µm or less.

- The solder according to chaim 1, wherein said solder having a liquidus temperature of 240°C or lower.
- The solder according to claim 1, wherein said solder having a 20 liquidus temperature of 23  $\circ$ C or lower.
  - The solder according to claim 1, wherein said solder has a

viscosity of 2.5 cP or lower.

The solder according to claim, further containing 0.02 to 0.06 wt% of Fe.

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The solder according to claim 1, further containing 0.02 to 0.05 wt% of Fe.

A lead-free solder consisting essentially of:

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- 1.0 to 4.0 wt% of Ag;
- (b)
  - 0.4 to 1.3 wt of Cu;
- (c)
- 0.02 to 0.06 wt% of Fe; and
- (d) a balance of Sn;

wherein said Fe serves to lower a copper dissolution rate

- 15 of said solder.
  - The solder according to claim 9, wherein a content of Fe is in a range from 0.02 to 0.05 wt%.
- 11. The solder according to claim 9, wherein said solder having 20 ą copper dissolution rate of 0.20 μm or less.
  - The solder according to claim 9, wherein said solder having

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a liquidus temperature of 240°C or lower.

13. The solder according to claim 9, wherein said solder having a liquidus temperature of 230°C or lower.

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- 14. The solder according to claim 9, wherein said solder has a viscosity of 2.5 cP or lower.
- 15. A method of surface-treating a PWD, comprising the steps of:
- preparing said solder according to claim 1; and 10 (a)
  - (b) selectively coating said solder on a Cu circuit layer of a PWB.
  - A method of surface treating a PWD, comprising the steps of:
- (a) preparing sald/solder according to claim 7; and
  - (b) selective/y chating said solder on a Cu circuit layer of a PWB.
  - A method of surface-treating a PWD, comprising the steps of:
- 20 preparing said solder according to claim 9; and (a)
  - (b) selectively coating said solder on a Cu circuit layer of
  - a PWB

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- 18. A method of mounting electronic parts on a PWD comprising the steps of:
- preparing said solder according to claim 1; and
- soldering electronic parts on a Cu circuit layer of a PWB (b)
- with said solder.

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- 19. A method of mounting electronic parts on a PWD comprising the steps of:
- (a) preparing said solder according to claim 7; and
- (b) soldering electronic parts on a Cu circuit layer of a PWB with said solder.
- 20. A method of mounting electronic parts on a PWD comprising the steps of:
- 15 preparing said solder according to claim 9; and (a)
  - soldering electronic parts on a Cu circuit layer of a PWB (b) with/said solder.